

**Features:**

- Non-Isolated. Mounting base as common anode cathode terminal.
- Pressure contact technology with Increased power cycling capability
- Low forward voltage drop

**Typical Applications:**

- Welding Power Supply.
- Various Dc power supplies.

<b>V<sub>RRM</sub></b>	Type & Outline		
	800V	1000V	1200V
1400V	MDx200-14-213F4		
1600V	MDx200-16-213F4		
1800V	MDx200-18-213F4		

MDx stands for any type of **MDG, MDY**

<b>SYMBOL</b>	<b>CHARACTERISTIC</b>	<b>TEST CONDITIONS</b>	<b>T<sub>j</sub>(°C)</b>	<b>VALUE</b>			<b>UNIT</b>
				<b>Min</b>	<b>Type</b>	<b>Max</b>	
I <sub>F(AV)</sub>	Mean forward current	180° half sine wave 50Hz Single side cooled, T <sub>c</sub> =100°C	150			200	A
I <sub>F(RMS)</sub>	RMS forward current					314	A
I <sub>RRM</sub>	Repetitive peak current	at V <sub>RRM</sub>	150			20	mA
I <sub>FSM</sub>	Surge forward current	V <sub>R</sub> =60%V <sub>RRM</sub> , t=10ms half sine	150			6.2	kA
I <sup>2</sup> t	I <sup>2</sup> t for fusing coordination					192	10 <sup>3</sup> A <sup>2</sup> s
V <sub>FO</sub>	Threshold voltage		150			0.80	V
r <sub>F</sub>	Forward slope resistance					0.96	mΩ
V <sub>FM</sub>	Peak forward voltage	I <sub>FM</sub> =600A	25			1.50	V
R <sub>th(j-c)</sub>	Thermal resistance Junction to case	At 180° sine. Single side cooled per chip				0.20	°C/W
R <sub>th(c-h)</sub>	Thermal resistance case to heatsink	At 180° sine. Single side cooled per chip				0.10	°C/W
F <sub>m</sub>	Terminal connection torque(M6)			4.5		6.0	N·m
	Mounting torque(M6)			4.5		6.0	N·m
T <sub>vj</sub>	Junction temperature			-40		150	°C
T <sub>stg</sub>	Stored temperature			-40		125	°C
W <sub>t</sub>	Weight				280		g
Outline				213F4			

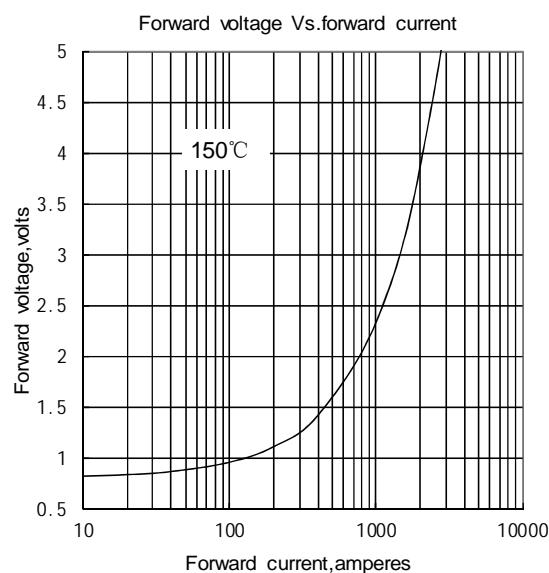


Fig.1

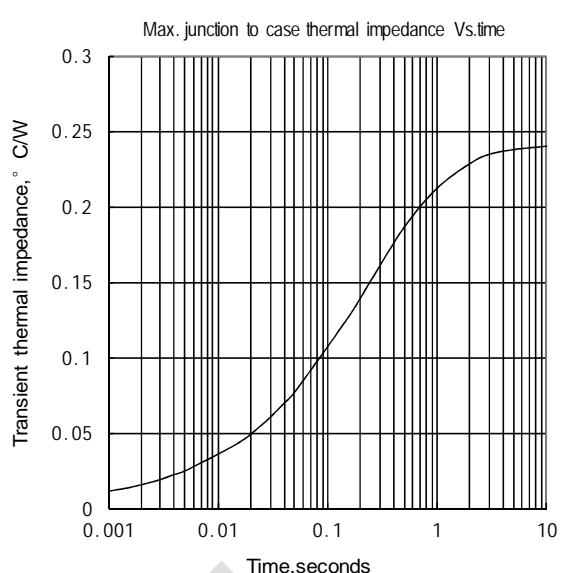


Fig.2

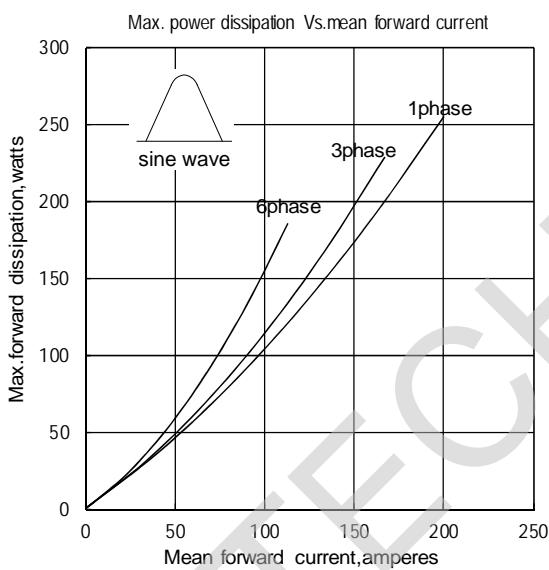


Fig.3

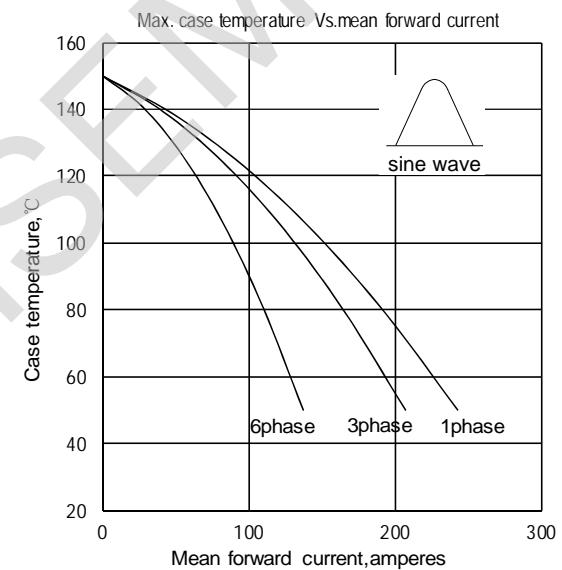


Fig.4

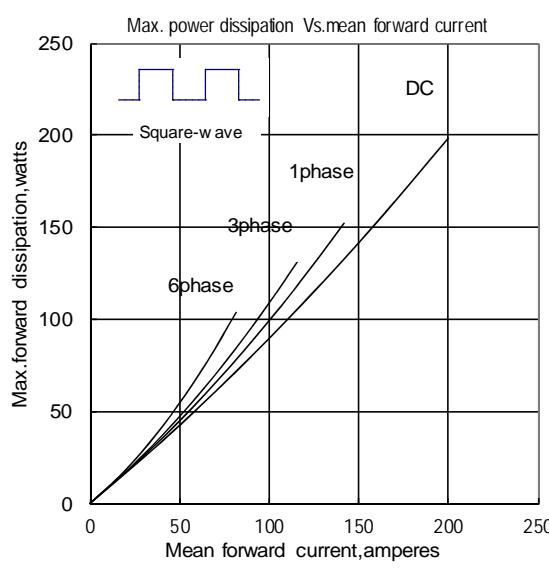


Fig.5

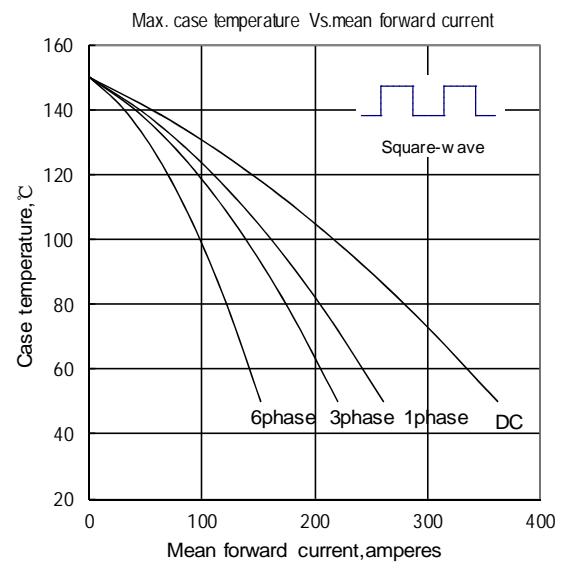


Fig.6

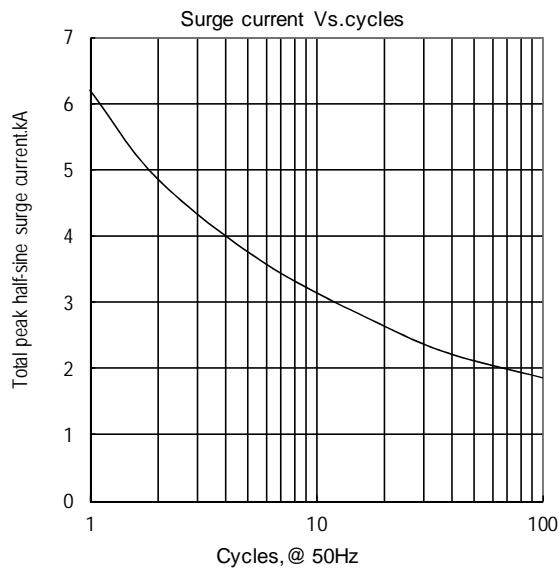


Fig.7

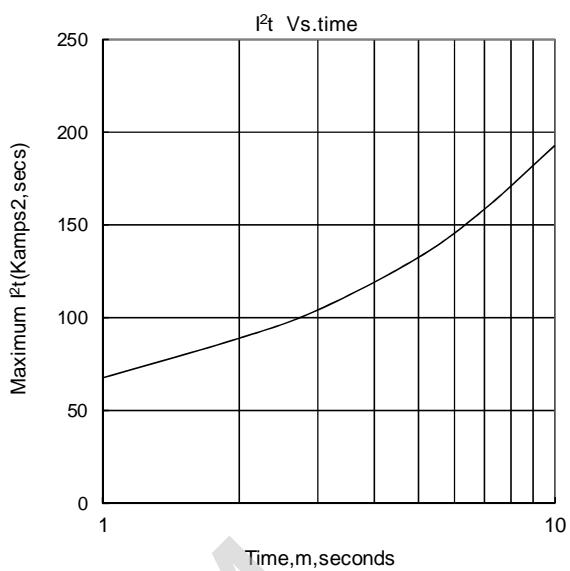
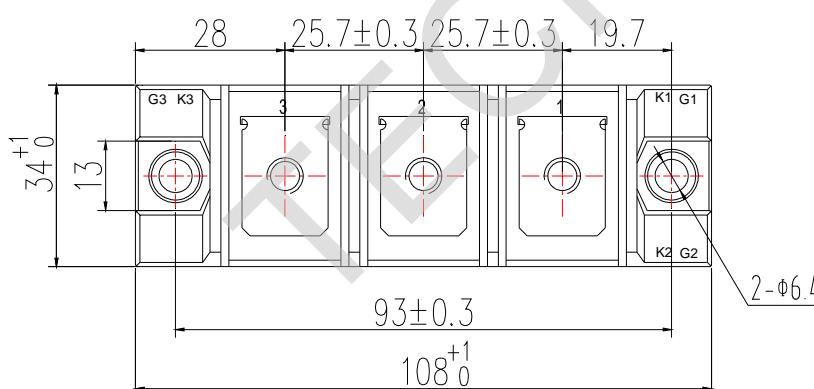
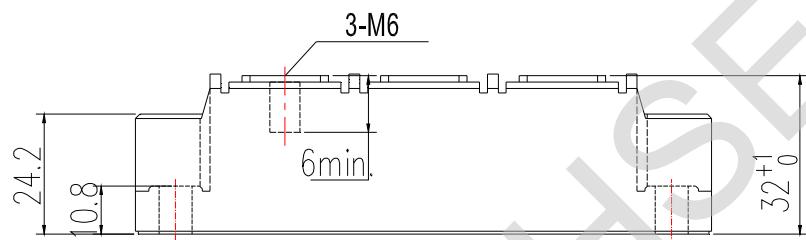
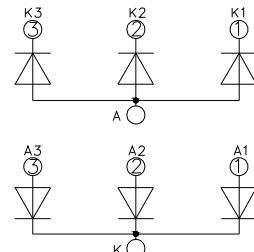


Fig.8

**Outline:**

MDG

MDY



Unmarked dimensional tolerance: ±0.5mm